

pvnanocell

Digital Printing of Electronics: Mass-Production Technologies & Applications

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PV Nano Cell April 20th, 2021

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pvnanocell



Founded 2009

Migdal HaEmek

20 People

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Conductive Inks

Process Inks Printers

Complete Solution

Current Massive Wave: Electronics Everywhere

PV Nano Cell's Digital Printing Solution Enables Electronics Everywhere









IoT

Applications











Medical

Devices



Smart

Packaging



Self-Driving Cars

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Customer Needs a PhD in Printed Electronics



PVN's Complete Solution Makes it as Easy as Driving



PV Nano Cell's Offering: 5D Technology



Complete Solution Linking: Chemistry, Printers & Process



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Families of SicrysTM – Single Crystal Nano Inks



High metal load, over 60%
Stability: Shelf life – over 12 months
Low sintering temperature (< 130 °C).
Low resistivity: ρ < 2.5 x bulk.

- Narrow pattern printing as narrow as 50 μm.
- Lower viscosity at high metal loading (50%+).
- Green & clean process, no hazardous material.
- SMT/soldering-capable.

Sicrys[™] Digital Silver Inks: Technical Characteristics

Ink properties	120DM-206	I40DM-106	150DM-106	I50TM-115	I50TM-119	I50T-13	130EG-1	I60PM-116
Metal Loading (% w/w)	20%	40%	50%	50%	50%	50%	30%	60%
Main Solvent ¹	DGME	DGME	DGME	TGME	TGME	TPM	EG	PM/DGME
Typical Viscosity @ 25°C (cP)	5	11	20	37	34	26	28	26
Surface Tension (dyn/cm) (Pendant Drop method)	34	34	34	36	29	26	47	23
Open Time ² (jetting temperature,°C)	15 min (25°C)	10 min (30°C)	10 min (30°C)	30 min (40°C)	10 min (35°C)	60 min (35°C)	5 min (35°C)	
Resistivity (μΩcm) (thermal sintering,°C, min)	≤ 10 (150,30) ≤ 12 (130,30)	≤ 10 (150,30) ≤ 12 (130,30)	≤ 10 (150,30) ≤ 12 (130,30)	≤ 10 (150,30) ≤ 12 (130,30)	≤ 10 (150,30) ≤ 12 (130,30)	≤ 10 (200,30) ≤ 24 (150,30)	≤ 10 (180,30) ≤ 14 (150,30)	≤ 10 (130,60)
Sheet Resistance (mΩ/□) (thickness, μm)	10 (10 μm)	10 (10 μm)	10 (10 μm)	100 (1 μm) 20 (4 μm)	30 (3.5 μm) 15 (8 μm)	100 (1 μm) 25 (4 μm)	100 (1 μm) 25 (4 μm)	
Substrate Adhesion ³ (tested) ⁴	ITO, Glass	ITO, Glass	ITO, Glass	ITO, Glass, PET, PC	Kapton [®] , FR4, PET, PC, ITO, Glass, CTO	PC, PEN, PET	Kapton®, PC, PEN, LCP, Glass	Kapton®, PC, PA, PC/ABS, Glass
Compatible Printing Technologies	Inkjet	Inkjet	Inkjet	Inkjet	Inkjet	Inkjet	Inkjet, Aerosol	Aerosol
Compatible Printheads (tested) ⁴	Epson DemonJet Desktop printers	KM1024 KM1024i Ricoh E3 DMC-11610 Samba	KM1024 KM1024i Ricoh E3 DMC-11610 SapphireQS-10pl	KM1024 KM1024i KM512 Ricoh E3 SapphireQS-10pl	KM1024 KM1024i Ricoh E3	KM1024 KM1024i Ricoh E3 DMC-11610 SapphireQS-10pl	KM1024 KM1024i Ricoh E3 DMC-11610 Aerosol	Aerosol (pneumatic) atomizer)

Shelf life: 12 months. Storage at room temperature. No need to stir the inks.

¹ - Solvents: DGME - diethylene glycol methyl ether, TGME - triethylene glycol methyl ether, PM - propylene glycol methyl ether, EG - ethylene glycol, TPM - tripropylene glycol methyl ether

² - Ricoh E3 printhead

³ - Adhesion depends on substrate, sintering conditions, substrate pretreatment and pattern thickness (tested according to ASTM-3359-09 or ISO-2409)

⁴ - Substrates and printheads listed here were tested and perform well. Other substrates and compatible printheads may also be applicable.

Sicrys[™] Digital Silver Inks: Technical Characteristics

Ink properties	I50TM-119
Metal Loading (% w/w)	50%
Main Solvent ¹	TGME
Typical Viscosity @ 25°C (cP)	34



Sicrys[™] Digital Silver Inks: Technical Characteristics

Ink properties	I50TM-119	
Resistivity (μΩcm)	≤ 10 (150,30)	
(thermal sintering,°C, min)	≤ 12 (130,30)	
Substrate Adhesion ³	Kapton [®] , FR4, PET,	
(tested) ⁴	PC, ITO, Glass, CTO	
Compatible Printing	Inkjet	
Technologies		
Compatible Brinthoads	KM1024	
(tostod)4	KM1024i	
(lesteu)	Ricoh E3	

Sicrys[™] Digital Copper Inks: Technical Characteristics

Ink properties	IC25EG-1	IC40DM-7	IC50DM-7	IC50TM-8
Metal Loading (% w/w)	20%	40%	50%	50%
Main Solvent ¹	EG	DGME	DGME	TGME
Cu oxide in Cu nano-particles	< 10%	< 5%	< 5%	< 5%
Typical Viscosity @ 25°C (cP)	32	16	20	32
Surface Tension (dyn/cm) (Pendant Drop method)	47	28	28	30
Open Time ² (jetting temperature, °C)	5 min (35°C)	1.5 min (35°C) 1.5 min (35°C)		20 min (40°C)
Resistivity (μΩcm) - Laser sintering (Photonic sintering)	≤ 5 (≤ 32)	≤5	≤5	≤ 5
Resistivity (μΩcm) - Thermal sintering (°C, min, Argon)	≤ 90 (300, 30,Ar)	≤ 120 (300, 30, Ar)	≤ 120 (300, 30, Ar)	≤ 120 (300, 30, Ar)
Substrate Adhesion ³ (tested) ⁴	Kapton [®] , PA, LCP, Glass	Kapton [®] , FR4, ITO, Glass	Kapton [®] , FR4, ITO, Glass	Kapton [®] , FR4, ITO, Glass
Compatible Printing Technologies	Inkjet Aerosol	Inkjet	Inkjet Aerosol	Inkjet
Compatible Printheads ⁴	KM1024 KM1024i Ricoh E3 Aerosol	KM1024 KM1024i Ricoh E3 DMC-11610	KM1024 KM1024i Ricoh E3 Aerosol	KM1024 KM1024i Ricoh E3
Shelf life: 12 months. Storage at room temperatur of time (minutes), refill the bottle with Argon ever ¹ - Solvents: EG - ethylene glycol, DGME - diethylene	e under Argon. No need y time the bottle is oper	to stir the ink. Copper ned.	ink can be exposed to	air for short periods

² - Ricoh E3 printhead

³ - Adhesion depends on substrate, sintering conditions, substrate pretreatment and pattern thickness (tested according to ASTM-3359-09 or ISO-2409)

⁴ - Substrates and printheads listed here were tested and perform well. Other substrates and compatible printheads may also be applicable

Sicrys[™] Digital Copper Inks: Technical Characteristics

	Ink properties	IC25EG-1		
Resi	stivity (μΩcm) - Laser sintering (Photonic sintering)	≤ 5 (≤ 32)		
Resist	ivity (μΩcm) - Thermal sintering (°C, min, Argon)	≤ 90 (300, 30,Ar)		
S	ubstrate Adhesion ³ (tested) ⁴	Kapton [®] , PA, LCP, Glass		
Cor	npatible Printing Technologies	Inkjet Aerosol		
	Compatible Printheads ⁴	KM1024 KM1024i Ricoh E3 Aerosol		



Ink Production Process



Inkjet Printing Capabilities

 $Width > 50 \mu m$







<u>0.7 μm < Thickness <10 μm</u>







PET

Glass

ITO

Polycarbonate

Etc.

200 J/cm², 1,000 mW, 5 mm/s, ρ =5.2 μ ncm 8 J/cm², 5,000 mW, 200 mm/s, ρ =4.8 μ ncm

Inkjet Printing: >50 µm Width & Pitch, >1 µm Thickness













Commercial Applications: Automotive Market

Windshields are filled with Electronics

- Multi inks printed using one printer.
- Narrow & dense electronics.
- Large format
- Each windshield is different.



- Bus Bars Resistivity: $1.5 \text{ m}\Omega/\Box$
- Fine Lines Width < 0.6 mm
- Fine Lines Resistivity: 2.0 m Ω/\Box





Electronics Everywhere: Automotive Market Future Technologies

<u>"Smart" Connectors by Molex</u>

- Narrow & thin patterns.
- Low resistances at low sintering temperatures.
- 2.5D and 3D printing.
- Usage: light bulbs, power charging, etc.







Project Tinker

- Radar and LiDAR sensor package fabrication.
- High throughput of up to 250 units/min.
- PVN is sole provider of conductive ink for next generation of automotive electronics.
- \$12M EU funded project.











Automotive Windshield

PCB on FR4 Resistivity < 10 μΩcm, Thickness <10 μm. Special Heater on FR4, Inkjet printed 600 µm vias







4-Layer PCB Resistivity < 6 μΩcm, Thickness 20 μm

1-Layer PCB Inkjet Printed Conductive, Solder Mask & Legends Coil with 18 Turns Linewidth 70 μm. Pitch 70 μm.



Commercial 11W Heater on Kapton[®] Linewidth 150 μm. Thickness 2 μm.





Flexible Antenna

RFID Tag







Phone Antenna Aerosol Printing, Resistivity < 12 μΩcm Silicon Crystalline Solar Sell Linewidth 50 μm, Resistivity < 3 μΩcm. Medical Sensor on Paper Resistance < 20Ω / 100mm

Printed Antennas







Wearable Frame

Wi-Fi / Bluetooth

Battery Cover

NFC on Flex

Electronic Housing

4 Antennas on Cover

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Embedded Passive Components



Coil with 18 Turns. 70 μ m Width & Pitch. Resistivity: 10 μ Ωcm. Printed on FR4.

Selected Resistance Results on Glass						
Sample #	width [µm]	Thickness [μm]	Resistance [Ω]	SR [Ω/sq]	Width [μm]	
1	70	0.7	1795	4.2	71.56	
2	90	0.8	1291	3.9	90.71	



Silver
Dielectric
Silver

Embedded Printed Capacitor

Selected Capacitance Results & Dielectric Constant Calculation							
Area = pad size	Meas. point #	Thickness [μm]	Average* [pF]	Standard Deviation*	Relative Dielectric constant ɛr		
5x1.5mm	1	13.6	7.7	5.3%			
	3	9	11.4	5.9%			
	5	11.75	8.3	5.2%	4.84		
	10	11.25	7.7	5.9%			
	12	7.35	11.6	4.9%			

*Over frequency capacitance

Embedded Printed Resistor

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